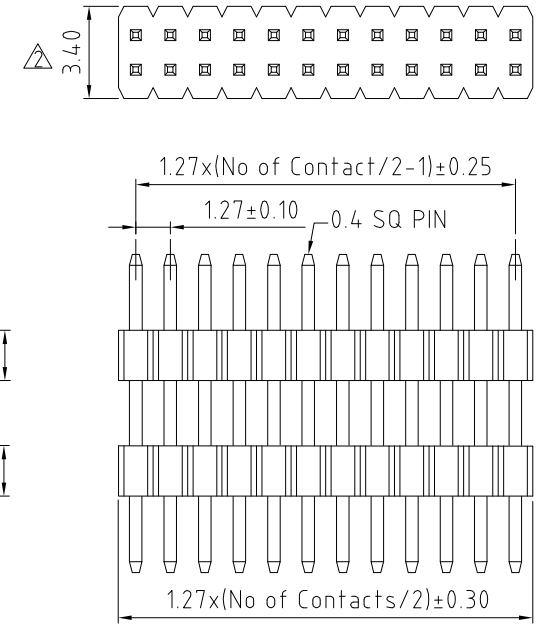
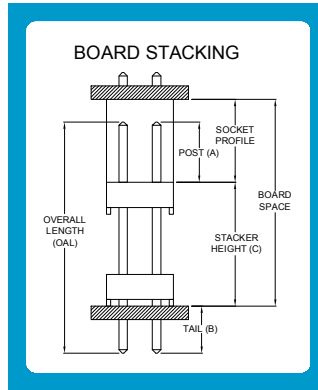


BB02-BP :- 1.27mm X 1.27mm (0.05" X 0.05") PIN HEADER, DUAL ROW, STRAIGHT, THROUGH HOLE TYPE - 04 TO 100 CONTACTS

SPECIFICATIONS

- CURRENT RATING: 1 AMP
- INSULATOR RESISTANCE: 1000 MEGOHMS MIN.
- DIELECTRIC WITHSTANDING: AC 300 V
- CONTACT RESISTANCE: 20m OHMS MAX
- OPERATING TEMPERATURE: -40°C TO +105°C
- CONTACT MATERIAL: BRASS
- INSULATOR MATERIAL: THERMOPLASTIC UL 94V-0
- STANDARD: LCP+30% G/F
- PLATING: GOLD, TIN, OR SELECTIVE OVER 30~50U" NICKEL
- SOLDERABILITY: LCP-IR REFLOW: 280°C FOR 10 SEC  
WAVE: 250°C FOR 5-10 SEC  
MANUAL SOLDER: 380°C FOR 3-5 SEC

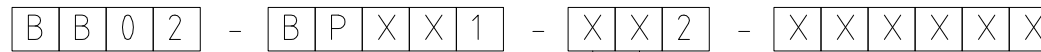


PACKED LOOSE IN BOX  $\Delta$   $\Delta$

- MATES WITH: - BB02-CL BB02-CU  
BB02-CM BB02-CW  
BB02-CN BB02-CX  
BB02-CQ BB02-CZ  
BB02-CR

NOTES:  
1. MAX. OAL (OVERALL PIN LENGTH A+C+B) = 34mm.

HOW TO ORDER



$\Delta$  NO. OF CONTACTS:  
04 TO 66 (FOR H OPTIONS = A, C, D, E.)  
OR  
04 TO 100 (100= 00, FOR H OPTION = B.)

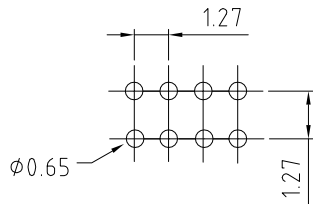
CONTACT PLATING OPTIONS:  $\Delta$   
K = GOLD FLASH (STANDARD)  
A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL  
B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL  
C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL  
T = BRIGHT TIN  
M = MATT TIN  
D = GOLD FLASH ON CONTACT/BRIGHT TIN ON TAIL  
E = 10U" GOLD ON CONTACT/BRIGHT TIN ON TAIL  
F = 15U" GOLD ON CONTACT/BRIGHT TIN ON TAIL  
G = 30U" GOLD ON CONTACT/BRIGHT TIN ON TAIL

$\Delta$  "H" OPTIONS:  
A = 2.5MM  
B = 1.0MM  
C = 2.0MM  
D = 1.5MM  
E = 3.0MM

PIN LENGTH A (1/10mm)  
SPECIFY PIN LENGTH  
MINIMUM = 10 = 1.0mm  
MAXIMUM = 150 = 15.0mm  
TOL.: ±0.25mm

PIN LENGTH C (1/10mm)  
SPECIFY PIN LENGTH  
MINIMUM = H HEIGHT x 2  
MAXIMUM = SEE NOTE: 1  
TOL.: ±0.25mm

PIN LENGTH B (1/10mm)  
SPECIFY PIN LENGTH  
MINIMUM = 10 = 1.0mm  
MAXIMUM = 150 = 15.0mm  
TOL.: ±0.25mm



RECOMMENDED PC BOARD HOLE LAYOUT (TOLERANCE: ±0.05)

LONGER PIN LENGTH REQUIRED?  
If pin length required is longer than 9.9mm (99), then use a '/' to separate the numbers.  
Example: A=6.0mm, C=12.5mm, B=3.0mm, mark as 60 / 125 / 30.

REV. DATE & DRN
10 22/02/02 - ASMT RELEASE
11 02/07/02 - AMEND PACK OPTION
12 12/07/05 - NYW REMOVE PIN OPTION A & B.
12 12/07/05 - NYW AMEND INSULATOR OPTION
13 15/07/05 - NYW AMEND PLATING OPTION
13 15/07/05 - NYW AMEND NO. OF CONTACTS
14 19/07/06 - NYW AMEND INSULATOR OPTION
14 19/07/06 - NYW DRAWING MODIFICATION
15 02/05/07 - NYW AMEND INSULATOR OPTION
15 02/05/07 - NYW AMEND PACKAGING & SOLDERABILITY.
16 30/04/08 - NYW AMEND INSULATOR MATERIAL
16 30/04/08 - NYW PLATING MODIFICATION
17 02/12/08 - CHC CHANGE PLASTIC TO LCP.
17 02/12/08 - CHC DRAWING MODIFICATION
18 25/02/09 - CHC DRAWING MODIFICATION
19 21/02/13 - NYW AMEND OAL TO 34MM.

Scale: 5:1
Drawn: CHC
App'd: XXXX
Date: 21 FEB. '13

THIRD ANGLE
Title PIN HEADER
Revision: 1.9

Unstated Tolerances:
X ± 0.30
XX ± 0.25
XXX ± 0.15
XXX ± 0.10

Material SEE NOTE
NOT TO SCALE
UNIT: mm

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Type: BB02-BP
BB02-BP
Drawing Number:
Sheet 1 of 1
Drawing © E and O E